ON Semiconductor®

Product Bulletin

Document # : PB22350X
Issue Date: 26 June 2018

Title of Change:	FOD819 datasheet update
Effective date:	26 June 2018
Contact information:	Contact your local ON Semiconductor Sales Office or <chingaik.yeoh@onsemi.com>
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	☐ Wafer Fab ☐ Assembly Change ☐ Test Change ☑ Other DATASHEET

Change Sub-Category(s):

☐ Manufacturing Site Addition
☐ Manufacturing Site Transfer
☐ Manufacturing Process Change

☐ Material Change
☐ Product specific change

☑ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________________

Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None

Description and Purpose:

Update FOD819 datasheet specs :

- The Storage temp, Operating temp and Junction temp from -40degC to -55degC.
- Revise the BVCEO from 40V to 80V.

Improving the product existing specification and performance, so the change will not impact the customer applications.

The update in datasheet will not impact form, fit, or function of product(s).

List of Affected Parts:

FOD819
FOD819S
FOD819SD